



**TM12N06D**

**N-Channel Enhancement Mosfet**

**General Description**

- Low  $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

**Applications**

- Load switch
- PWM

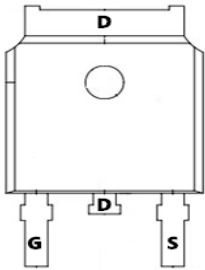
**General Features**

$V_{DS} = 60V$   $I_D = 12 A$

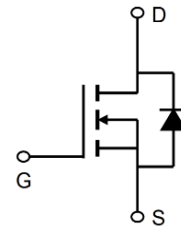
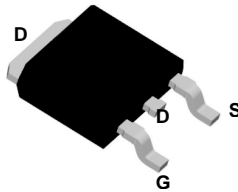
$R_{DS(ON)} = 58 m\Omega$  (typ.) @  $V_{GS} = -10V$

100% UIS Tested

100%  $R_g$  Tested



TO-252-3L



Marking : 12N06

**Absolute Maximum Ratings** ( $T_A=25^\circ C$  unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	$V_{DS}$	60	V
Gate-source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current	$I_D$	$T_A=25^\circ C$	12
		$T_A=100^\circ C$	8
Pulsed Drain Current <sup>A</sup>	$I_{DM}$	18	A
Total Power Dissipation <sup>B</sup>	$P_D$	$T_A=25^\circ C$	1.2
		$T_A=100^\circ C$	0.45
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~+150	$^\circ C$

**Thermal resistance**

Parameter	Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient <sup>C</sup>	$R_{\theta JA}$	85	105	$^\circ C/W$



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Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	60	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0V$	-	-	1	$\mu A$
		$V_{DS}=60V, V_{GS}=0V, T_J=150^\circ\text{C}$	-	-	100	
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.9	1.35	2	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=3A$	-	58	70	m $\Omega$
		$V_{GS}=4.5V, I_D=3A$	-	65	82	
Diode Forward Voltage	$V_{SD}$	$I_S=3A, V_{GS}=0V$	-	0.85	1.2	V
Gate resistance	$R_G$	$f=1\text{MHz}, \text{Open drain}$	-	2	-	$\Omega$
Maximum Body-Diode Continuous Current	$I_S$		-	-	12	A
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=30V, V_{GS}=0V, f=1\text{MHz}$	-	500	-	pF
Output Capacitance	$C_{oss}$		-	28	-	
Reverse Transfer Capacitance	$C_{rss}$		-	22	-	
<b>Switching Parameters</b>						
Total Gate Charge	$Q_g$	$V_{GS}=10V, V_{DS}=30V, I_D=3A$	-	10	-	nC
Gate-Source Charge	$Q_{gs}$		-	1.7	-	
Gate-Drain Charge	$Q_{gd}$		-	2.1	-	
Reverse Recovery Charge	$Q_{rr}$	$I_F=3A, di/dt=100A/\mu s$	-	7	-	nC
Reverse Recovery Time	$t_{rr}$		-	33	-	ns
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=10V, V_{DD}=30V, R_L=20\Omega$ $R_{GEN}=3\Omega$	-	3.6	-	ns
Turn-on Rise Time	$t_r$		-	17.6	-	
Turn-off Delay Time	$t_{D(off)}$		-	13	-	
Turn-off fall Time	$t_f$		-	23	-	

A. Repetitive rating; pulse width limited by max. junction temperature.

B.  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.

C. The value of  $R_{\theta JA}$  is measured with the device mounted on the minimum recommend pad size, in the still air environment with  $T_A=25^\circ\text{C}$ . The maximum allowed junction temperature of  $150^\circ\text{C}$ . The value in any given application depends on the user's specific board design.



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Typical Electrical and Thermal Characteristics Diagrams

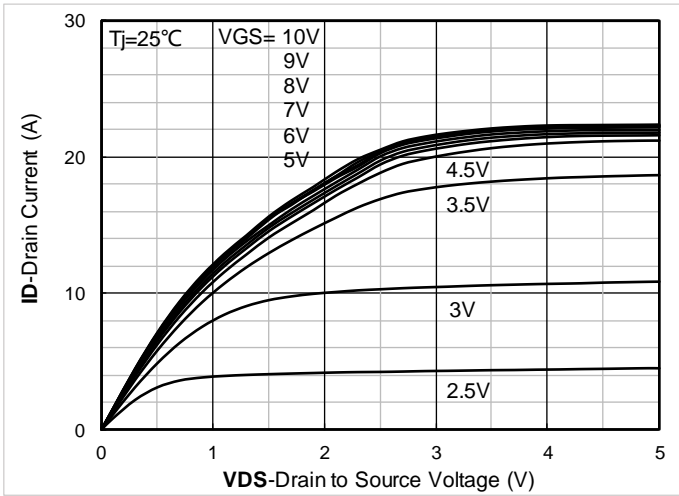


Figure 1. Output Characteristics

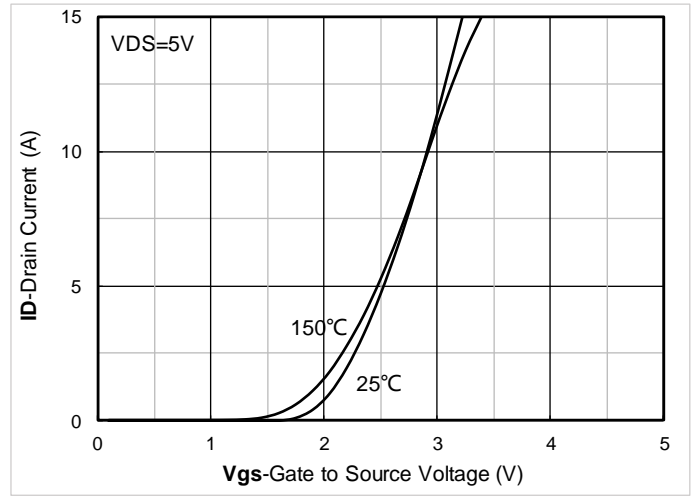


Figure 2. Transfer Characteristics

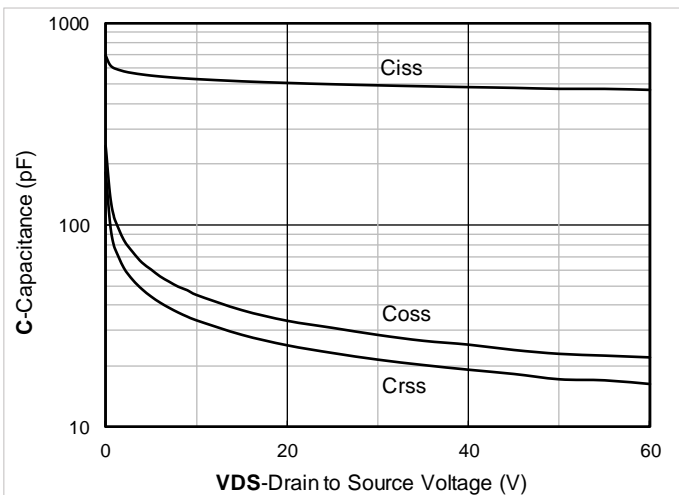


Figure 3. Capacitance Characteristics

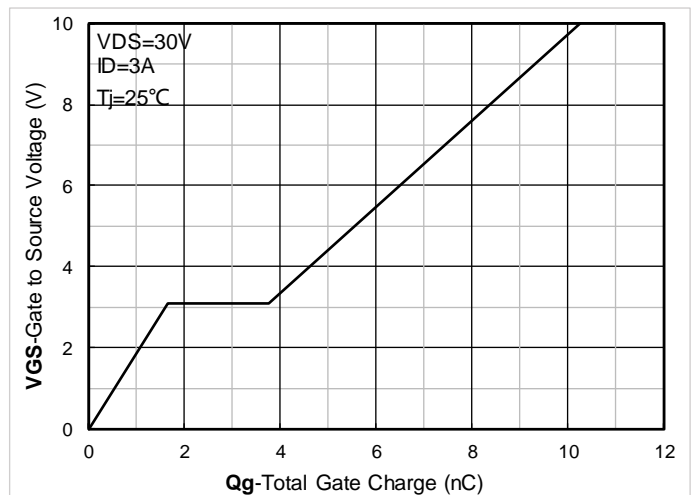


Figure 4. Gate Charge

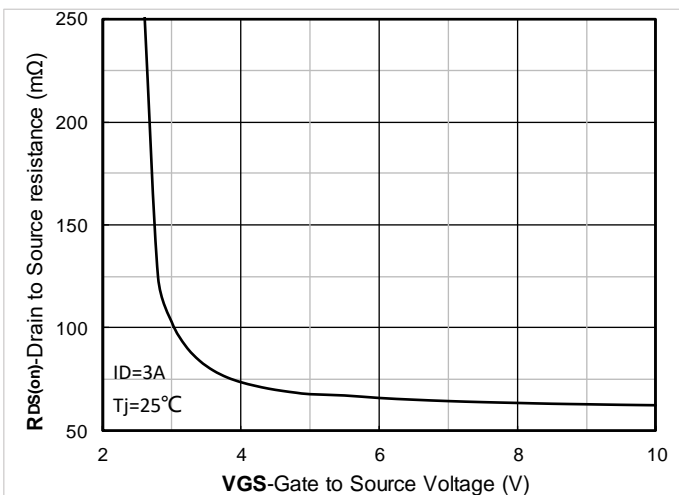


Figure 5. On-Resistance vs Gate to Source Voltage

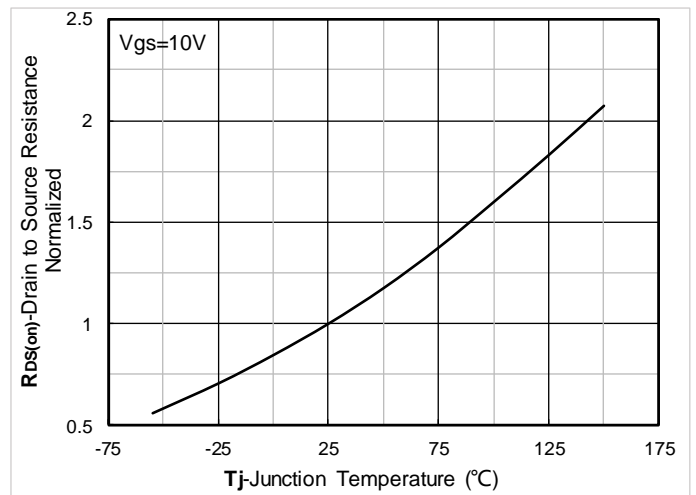


Figure 6. Normalized On-Resistance



TM12N06D

N-Channel Enhancement Mosfet

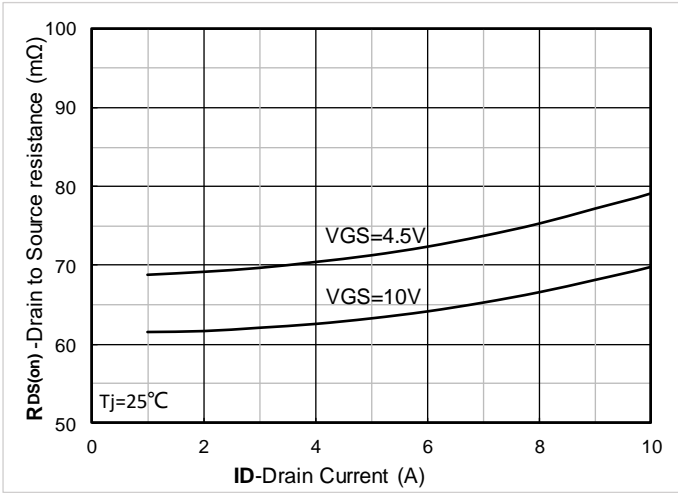


Figure 7. RDS(on) VS Drain Current

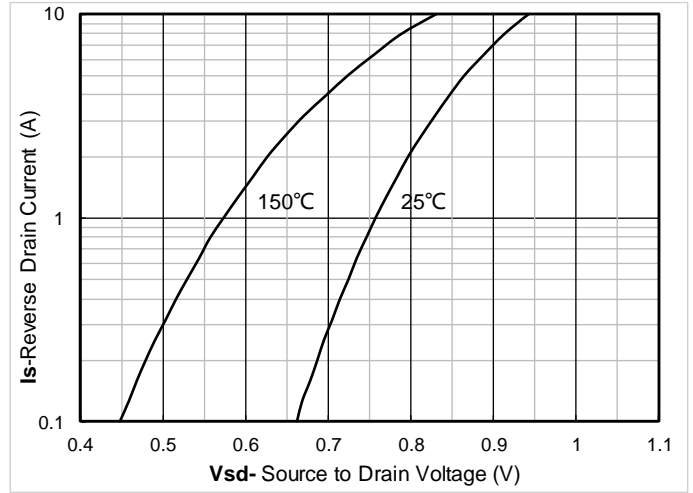


Figure 8. Forward characteristics of reverse diode

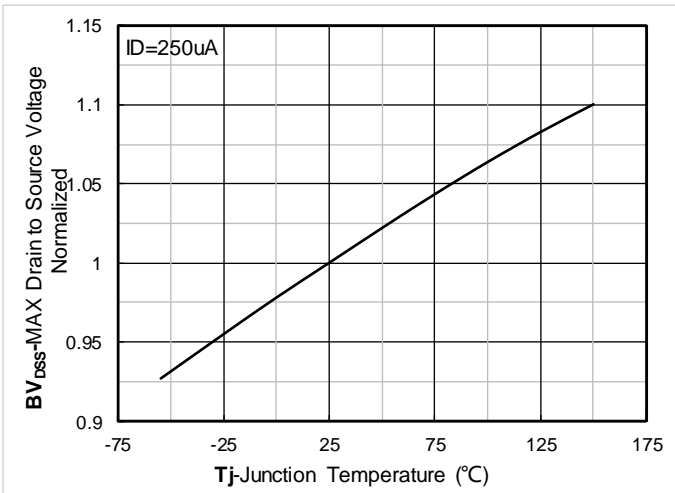


Figure 9. Normalized breakdown voltage

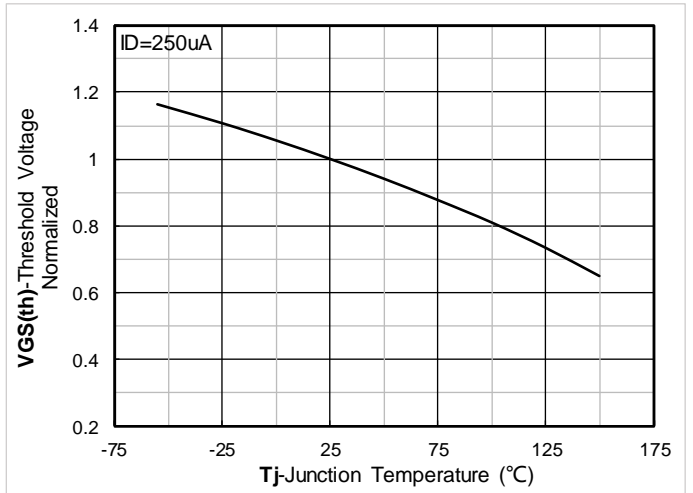


Figure 10. Normalized Threshold voltage

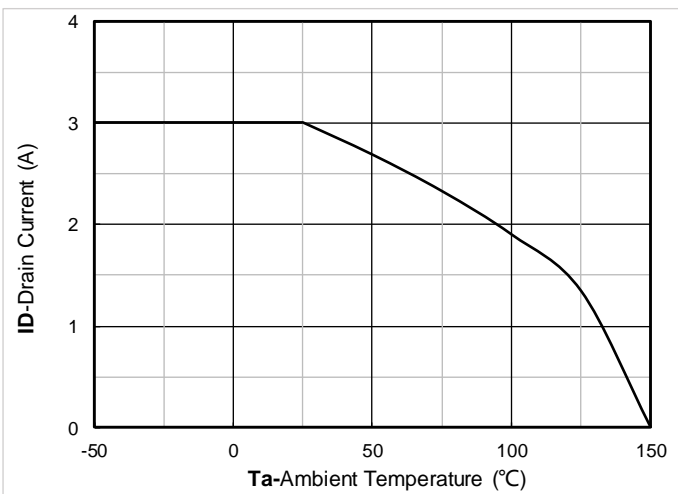


Figure 11. Current dissipation

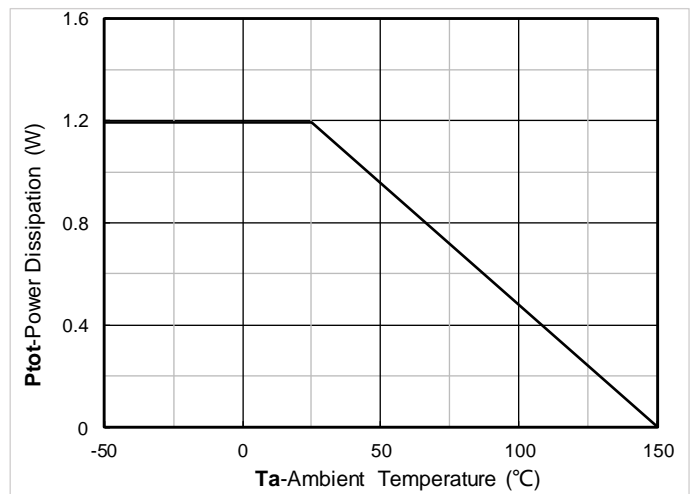


Figure 12. Power dissipation



TM12N06D

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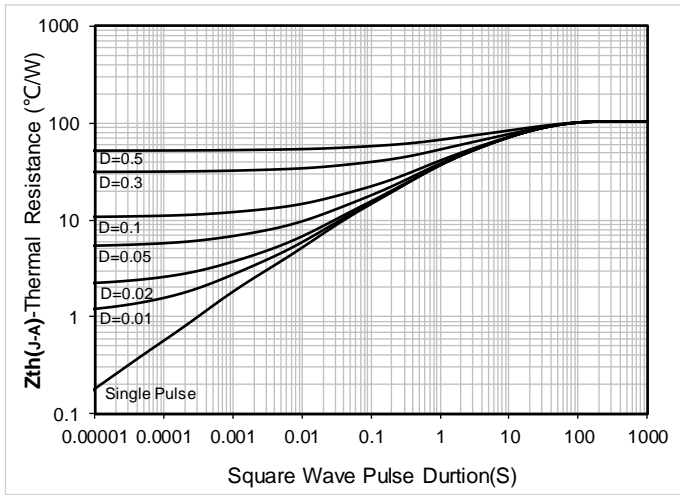


Figure 13. Maximum Transient Thermal Impedance

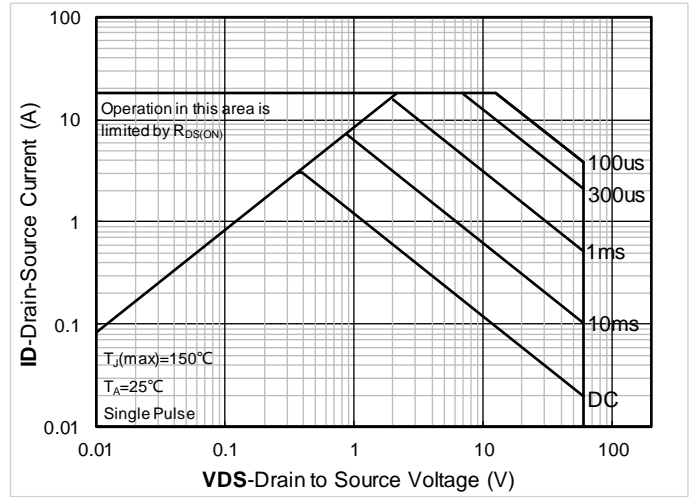


Figure 14. Safe Operation Area

Test Circuits & Waveforms

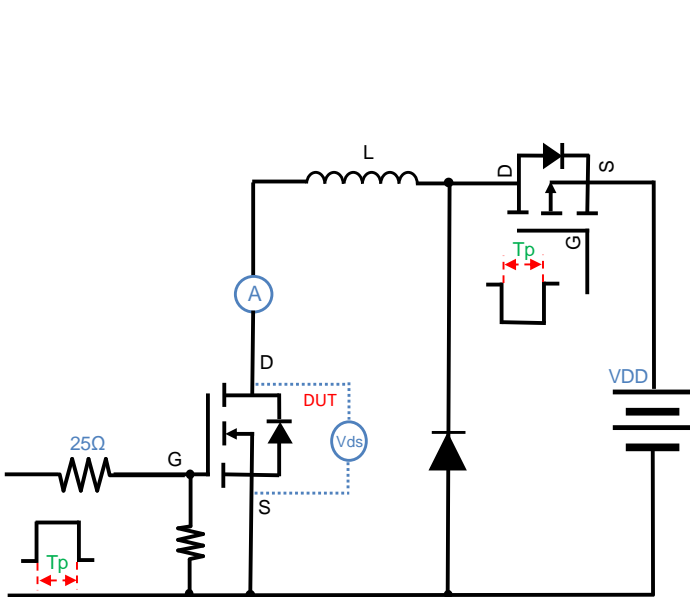
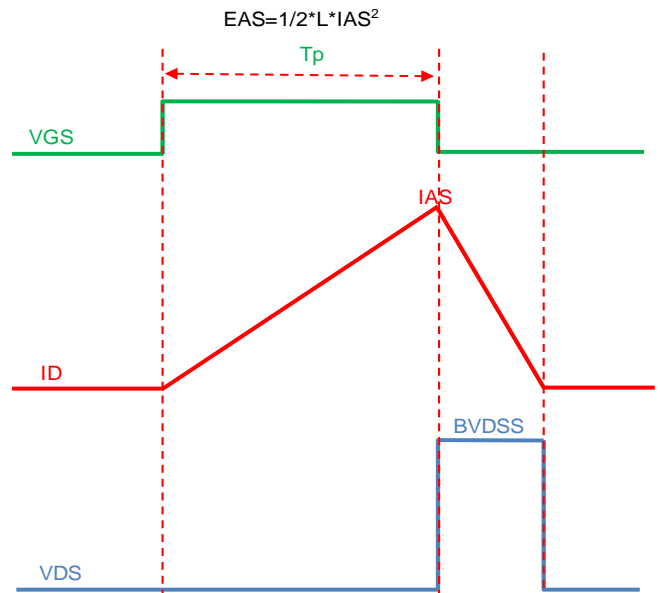


Figure A. Unclamped Inductive Switching (UIS) Test Circuit & Waveform





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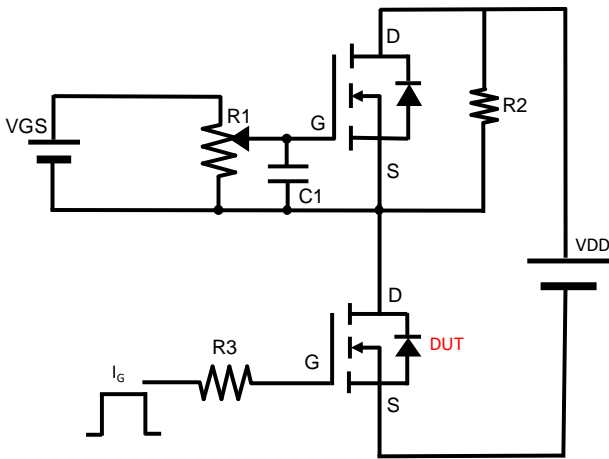


Figure B. Gate Charge Test Circuit & Waveform

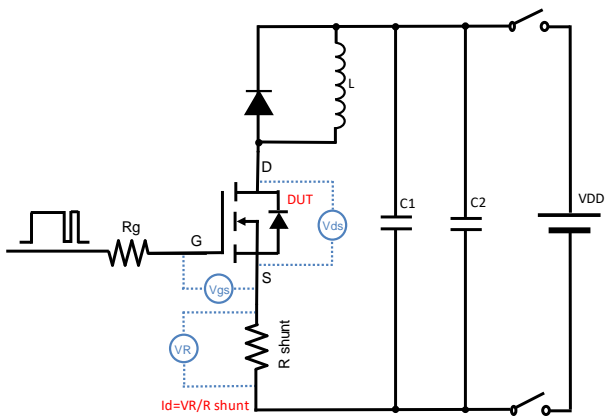


Figure C. Resistive Switching Test Circuit & Waveform

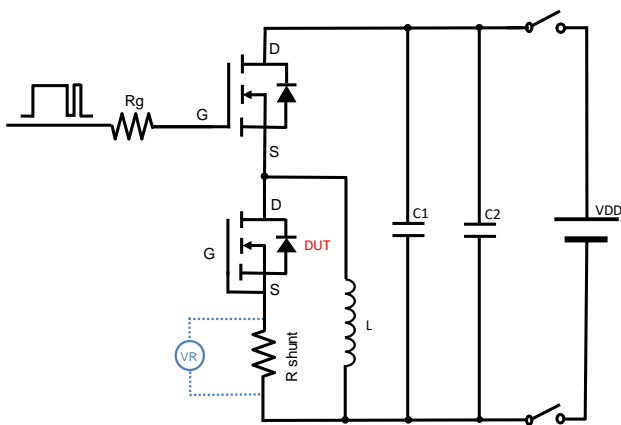
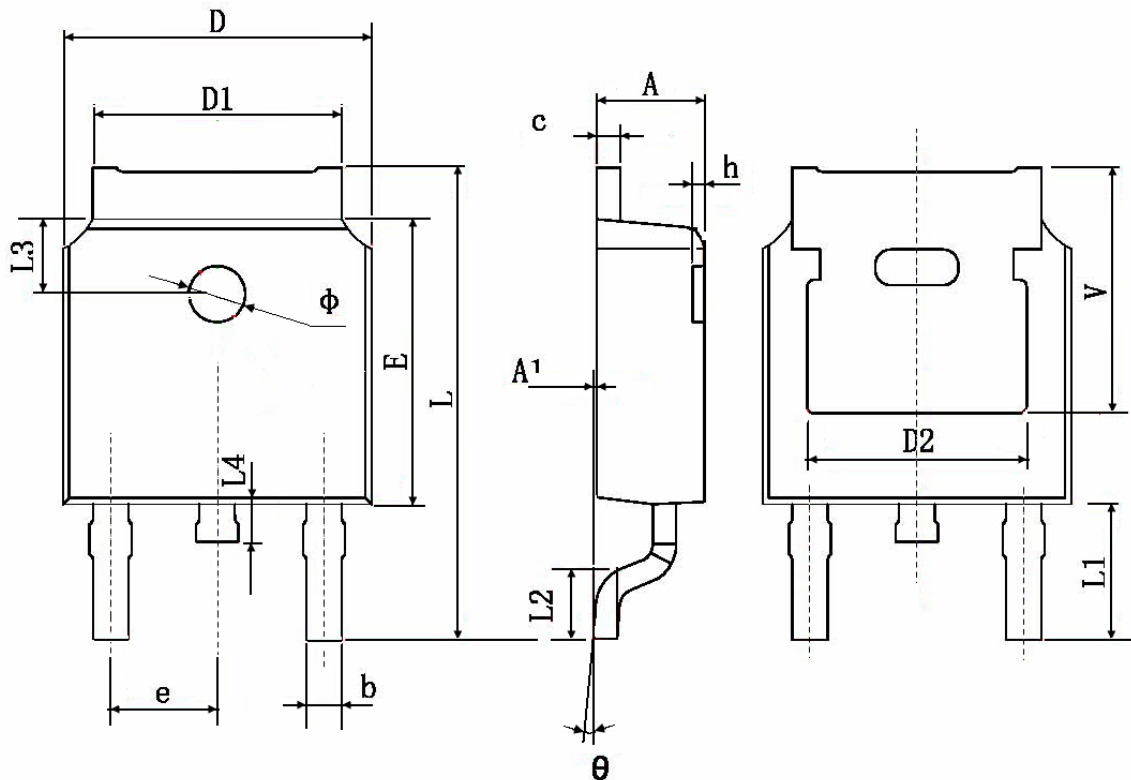


Figure D. Diode Recovery Test Circuit & Waveform

**Package Information:TO-252-3L**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
phi	1.100	1.300	0.043	0.051
theta	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	